



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



Contact us

Tel: +86-755-8981 8866 Fax: +86-755-8427 6832

Email & Skype: info@chipsmall.com Web: www.chipsmall.com

Address: A1208, Overseas Decoration Building, #122 Zhenhua RD., Futian, Shenzhen, China



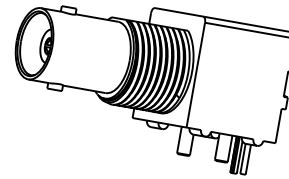
NOTES:

1. MATERIALS AND FINISHES:
 BODY - ZINC DIE CAST, NICKEL PLATING
 CONTACT - PHOSPHOR BRONZE, GOLD PLATING (.000003 THICK)
 @ CONTACT AREA ONLY, TIN PLATING AT TAIL, NICKEL PLATED OVERALL
 INSULATOR - POLYPROPYLENE
 HOUSING - PBT, BLACK
 ROUND PIN - BRASS, TIN PLATING
 GROUNDING TERMINAL - STEEL, TIN PLATING
2. ELECTRICAL:
 A. IMPEDANCE: 50 OHM
 B. FREQUENCY RANGE: DC - 1 GHz
 C. DIELECTRIC WITHSTANDING VOLTAGE: 1500 VRMS, MIN.
3. MECHANICAL:
 A. DURABILITY: 500 CYCLES MIN.
 B. TEMPERATURE RANGE: -55° C TO 85° C
4. PACKAGING:
 A. PACKAGED IN PACKING TRAYS
 B. QUANTITY PER TRAY: 40
5. SEPERATLY SUPPLIED MOUNTING HARDWARE
 TO BE TIGHTENED TO 10 IN-LBS MIN/15 IN-LBS MAX
 WHEN ASSEMBLING TO PANEL

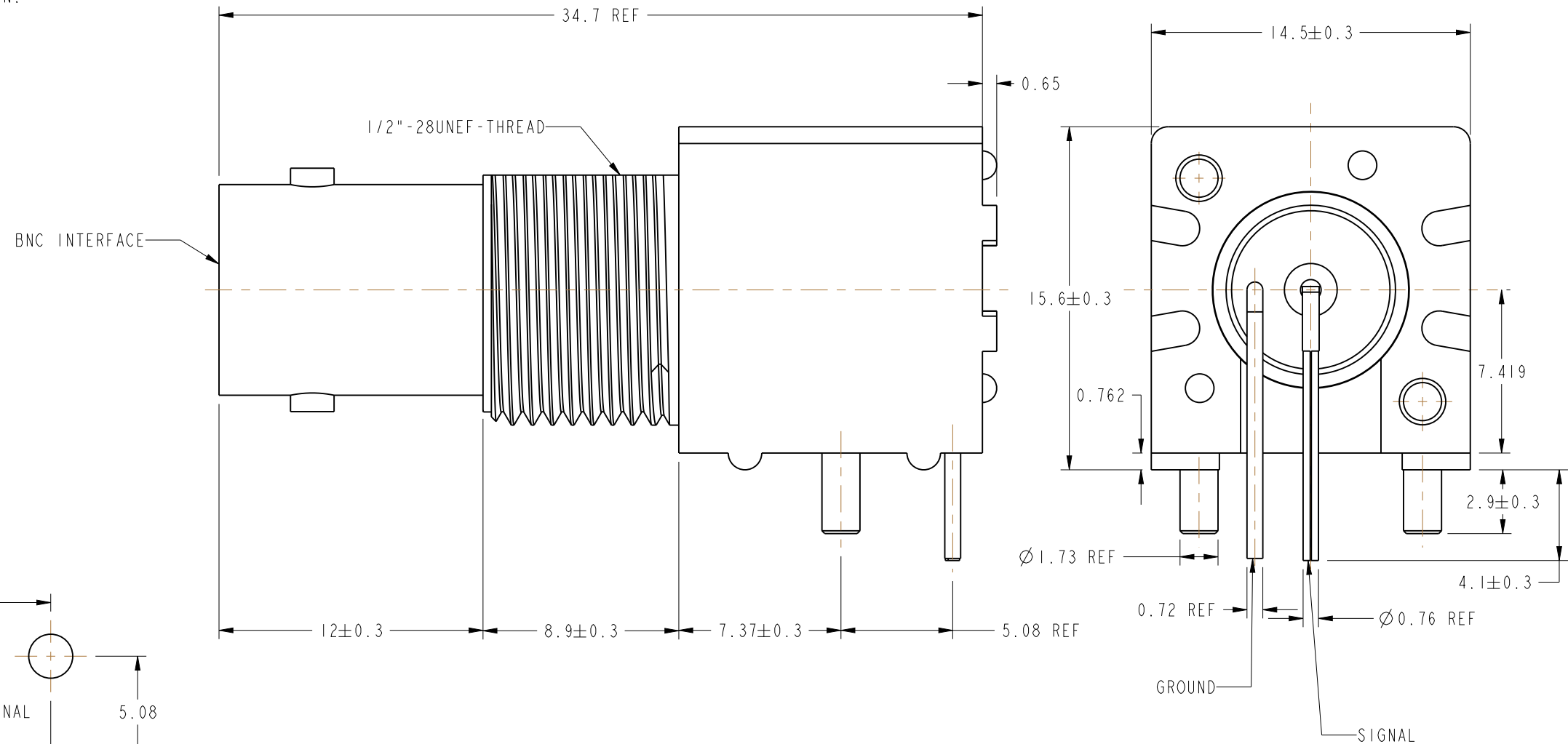
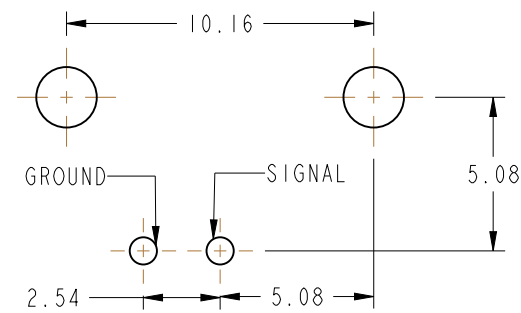
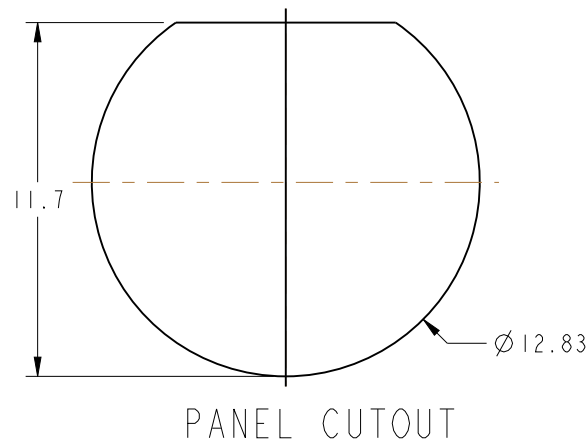
THIRD ANGLE PROJ.

REVISIONS

REV	DESCRIPTION	DATE	ECO	APPR
A	RELEASE TO MFG.	12/7/90	37726	DR
H	SEE SHEET I	2/3/05	45257	CPM
J	UPDATED FORMAT AND NOMINAL ENVELOPE DIMENSIONS	7/15/13	49574	EW



SCALE 1.000



CUSTOMER OUTLINE DRAWING

ALL OTHER SHEETS ARE FOR INTERNAL USE ONLY

UNLESS OTHERWISE SPECIFIED, DIMENSIONS ARE IN METRIC AND TOLERANCES ARE:
 <0.5mm ±0.05mm 0.5 - 6mm ±0.1mm 6 - 30mm ±0.2mm 30 - 120mm ±0.3mm ANGLES ±1°

NOTICE - These drawings, specifications, or other data (1) are, and remain the property of Amphenol corp. (2) must be returned upon request; and (3) are confidential and not to be disclosed to any person other than those to whom they are given by Amphenol Corp. the finishing of these drawings, specifications, or other data by Amphenol Corp., or to any other person to anyone for any purpose is not to be regarded by implication or otherwise in any manner licensing, granting rights to permitting such holder or any other sperson to manufacture, use or sell any product, process or design, patented or otherwise, that may in any way be related to or disclosed by said drawings, specifications, or other data.

MATERIAL	-
REFERENCE	
CONFIGURATION LEVEL:	
FINISH	

DRAWN	ERIC WANKOFF	DATE	20-Jun-12
ENGINEER	D ROYCE	DATE	20-Jun-12
APPROVED	D ROYCE	DATE	
CAD FILE			

TITLE	
50 OHM BNC R/A JACK, ISOLATED	
SCALE: 4.0:1.0	SHEET 2 OF 2
DWG SIZE B	REV J

Amphenol RF	
www.amphenolrf.com	
DRAWING NO. 31-5538	
ITEM NO. 31-5538	
PART NO. 31-5538	